

PROTECTION PRODUCTS - RailClamp®

Description

RailClamp[®] is a low capacitance TVS array designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to data and transmission lines from overvoltage caused by **ESD** (electrostatic discharge), **CDE** (Cable Discharge Events), and **EFT** (electrical fast transients).

The RClamp1644T is specifically designed to protect portable devices that utilize a uUSB port. The unique design of this device features low capacitance TVS diodes for protection of the USB data (DP, DM) and USB ID pins operating up to 5 volts. Loading capacitance on these lines is <0.6pF for maximum signal integrity. An integrated 12 volt TVS diode is used for protection of the USB voltage bus. This ensures the device will remain in a high-impedance state during normal USB operation or when the battery is being charged. Leakage current of the VBus protection is <50nA when operating at 12 volts.

The RClamp1644T is in a 6-pin SLP1508N5T package. It measures $1.5 \times 0.8 \times 0.40$ mm. The leads are spaced at a pitch of 0.35mm and are finished with lead-free NiPdAu. They may be used to meet the ESD immunity requirements of IEC 61000-4-2.

Features

- ESD protection for high-speed data lines to
 IEC 61000-4-2 (ESD) ±25kV (air), ±20kV (contact)
 IEC 61000-4-5 (Lightning) 10A (8/20μs)
 IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Protects USB DP, DM, and ID Pin operating to 5V
- Protects USB VBus operating up to 12V
- Low capacitance (<0.60pF) on DP, DM, and ID Pins
- Low clamping voltage
- Extremely low dynamic resistance: 0.33 Ohms (Typ) on DP, DM, and ID Pins
- Innovative flow-through design allows easy pcb layout
- Solid-state silicon-avalanche technology

Mechanical Characteristics

- SLP1508N5T 5L package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Nominal Dimensions: 1.5 x 0.8 x 0.40 mm
- Lead Finish: NiPdAu
- Molding compound flammability rating: UL 94V-0
- Marking : Marking code + date code
- Packaging : Tape and Reel

Applications

- USB 2.0
- USB OTG
- Micro USB

Circuit Diagram



Pin Configuration



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Absolute Maximum Rating

Rating	Symbol	Value	Units		
DP, DM, USB ID					
Peak Pulse Power (tp = 8/20µs)	P _{pk}	75	Watts		
Peak Pulse Current (tp = 8/20µs)	I _{PP}	5	A		
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±25 ±20	kV		
Operating Temperature	Tj	-55 to +125	°C		
Storage Temperature	T _{stg}	-55 to +150	°C		
VBus TVS		•			
Peak Pulse Power (tp = 8/20µs)	P _{pk}	300	Watts		
Peak Pulse Current (tp = 8/20µs)	I _{PP}	10	A		
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	±30 ±30	kV		
Operating Temperature	T,	-55 to +125	°C		
Storage Temperature	T _{stg}	-55 to +150	°C		

VBus TVS						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 1 to GND			12	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA, Pin 1 to GND	15	16.5	18	V
Reverse Leakage Current	I _R	V _{RWM} = 12V Pin 1 to GND		0.005	0.100	μA
Forward Voltage	V _F	I _r = 10mA GND to Pin 1	0.6		1.0	V
Clamping Voltage	V _c	I _{pp} = 10A, tp = 8/20µs Pin 1 to Ground			30	V
Forward Clamping Voltage	V _{FC}	I _{pp} = 10A, tp = 8/20µs Ground to Pin 1			3	V
Junction Capacitance	C _j	V _R = OV, f = 1MHz Pin 1 to GND		55	75	pF

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Electrical Characteristics (T=25°C)

DM, DP, USB ID

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 2, 3, or 4 to GND			5	V
Reverse Breakdown Voltage	V _{BR}	I _t = 1mA, Pin 2, 3, or 4 to GND	6.5	9	11	V
Reverse Leakage Current	I _R	V _{RWM} = 5.0V, Pin 2, 3, or 4 to GND		0.005	0.100	μA
Forward Voltage	V _F	I _f = 15mA Pin 2, 3, or 4 to GND	0.6		1.2	V
Clamping Voltage	V _c	I _{PP} = 1A, tp = 8/20µs Pin 2, 3, or 4 to GND			12	V
Clamping Voltage	V _c	I _{PP} = 5A, tp = 8/20µs Pin 2, 3, or 4 to GND			15	V
ESD Clamping Voltage	V _c	IPP = 4A, tlp = 0.2/100ns		12		V
ESD Clamping Voltage	V _c	IPP = 16A, tlp = 0.2/100ns		16		V
Dynamic Resistance	R _D	tp = 100ns		0.33		Ohms
Junction Capacitance	C _j	V _R = 0V, f = 1MHz, Pin 2, 3, or 4 to GND		0.45	0.60	pF
		V _R = 0V, f = 1MHz, Between I/O pins		0.20	0.4	pF

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Typical Characteristics

Non-Repetitive Peak Pulse Power vs. Pulse Time

EMTECH



5

5

0

0

25

-25

-30

-30

-25

VBus

20

15

10

TLP Voltage (V)

R_{DYN} = 0.25 Ohms

-5

0

DP, DM, ID

-20

R_{DYN} = 0.75 Ohms

-15

TLP Voltage (V)

-10

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Typical Characteristics

ESD Clamping (+8kV Contact per IEC 61000-4-2) DM, DP. ID Pins (Pins 2, 3, 4)











ESD Clamping (-8kV Contact per IEC 61000-4-2) DM, DP. ID Pins (Pins 2, 3, 4)



ESD Clamping (-8kV Contact per IEC 61000-4-2) VBus Pin (Pin 1)



Analog Crosstalk DM, DP. ID Pins (Pins 2, 3, 4)



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Applications Information

Device Connection and Layout Options for Protecting One USB Port

The RClamp1644T is optimized for protection of USB ports. Low capacitance protection is provided for the USB data (DM, DP) and USB ID pins. The maximum capacitance on these lines is <0.60pF. USB Data and ID lines are connected at pins 2, 3, and 4. These inputs are referenced to an internal 5 volt TVS protection device. When the voltage on these lines exceed 5 volts, the TVS will conduct. Pin 1 is connected to the USB voltage bus (VBus). This device will conduct when the voltage on the bus exceeds 12 volts. Ground is provided at pin 5. Multiple micro vias connected to ground are recommended for best ESD performance. This will reduce parasitic inductance in the ground path and minimize the clamping voltage seen by the protected device. The package is designed for easy trace routing. The VBus pin is connected to the voltage layer of the PCB with a micro via as shown. Connection to ground is made at pin 5 using two micro vias. Connection to the ID pin is shown, however if the application does not utilize the ID function, pin 4 can be left not connected. The flow through layout combined with extremely low capacitance means the RClamp1644T will have minimal effect on high speed signal integrity. A typical USB 2.0 eye diagram test result with RClamp1644T is shown in Figure 3.

Assembly Guidelines

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.



Figure 1 - Pin Configuration (Top View)



Figure 2 - PCB Layout Example



Figure 3 - USB Eye Pattern with RClamp1644T

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Applications Information

Assembly Parameter	Recommendation		
Solder Stencil Design	Laser cut, Electro-polished		
Aperture shape	Rectangular		
Solder Stencil Thickness	0.100 mm (0.004")		
Solder Paste Type	Type 4 size sphere or smaller		
Solder Reflow Profile	Per JEDEC J-STD-020		
PCB Solder Pad Design	Non-Solder mask defined		
PCB Pad Finish	OSP OR NiAu		



Figure 4 - Recommended Mounting Pattern

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Outline Drawing - SLP1508N5T



Land Pattern - SLP1508N5T



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PROTECTION PRODUCTS Marking Codes



Ordering Information

Part Number	Qty per Reel	Reel Size	
RClamp1644T.TNT	10,000	7 Inch	

RailClamp and RClamp are trademarks of Semtech Corporation.

YW = Date Code

Carrier Tape Specification



SECTION A-A

Device Orientation in Tape



Pin 1 Location (Towards Sprocket Holes)

User Direction of feed

Contact Information

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